CALL FOR PAPERS

62nd ECTC

ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE

May 29 – June 1, 2012

San Diego, California

OPTOELECTRONICS

Papers are solicited on all topics pertaining to the design, development, and technology of packaging active/passive, hybrid, integrated and nanoscale photonic components, devices, circuitry and systems

Topics of interest include:

- **Optical Components for Computer-Com:** Dense low-cost parallel optical transceivers; co-packaging of parallel optical modules with conventional ICs on MCMs; low-cost parallel fiber and waveguide optical coupling; massively parallel optical interconnects; board-level waveguides; optical backplanes; glass/polymer low cost optics/waveguides; active optical cables
- **Silicon Nano-Photonics Devices:** Active and passive optical devices in silicon (such as, modulators, detectors, waveguides, switches, couplers); photonic circuits; hybrid lasers; monolithic and hybrid integration techniques; high-speed performance; energy efficiency; micro-nano optical interconnects; assembly, processing, testing, characterization, reliability, thermal management.
- **Nano-Optics:** Optical and physical properties, nano- and meta-materials, integration of nano- and conventional materials; high-efficiency lasers; advanced packaging, assembly, test and reliability
- **High-Efficiency LEDs and High Power Lasers:** Package and optical design, assembly methods and automation, thermal management, reliability and aging effects, color temperature control, phosphors, volume manufacturing, high-power laser diodes, bars / stacks, fiber coupled modules, high-power VCSELs and fiber lasers packaging technologies including-pump diodes, beam combining, coupling, wavelength control.
- **Integrated Optical Sensors:** On-chip and packaged biological, chemical, pressure, temperature, humidity sensors, integrated spectrometer, MEMS sensors, sensor assembly utilizing optical fibers, waveguides, and free-space micro-optics.
- **Micro-optical System Integration and Photonic System-in-Package Technologies:** Integrated optics and heterogeneous integration, silicon and glass based interposer, optical vias; fiber optic connectors and hybrid integration, nano-photonics packaging; novel interconnection technology and coupling.
- **Photonic Package Manufacturing Technologies:** Low cost designs and cost reduction techniques, novel micro-optics, assembly methodology, precision assembly of optical components and automation technology; Substrates and housing; advanced thermal management

You are invited to submit a 750-word abstract via the ECTC Website http://www.ectc.net

Abstract On-Line Submission opened 25 August 2011

(PLEASE SELECT *OPTOELECTRONICS* AS YOUR *PRIMARY COMMITTEE* FOR SUBMISSION)

(You may also submit directly to the committee chairs below – please include mailing address, telephone number, FAX number and e-mail):

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Abstracts Due: October 10, 2011